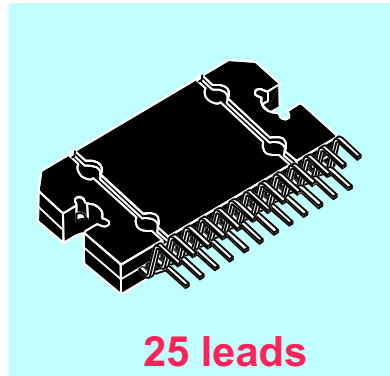


FLEXIWATT 25 leads



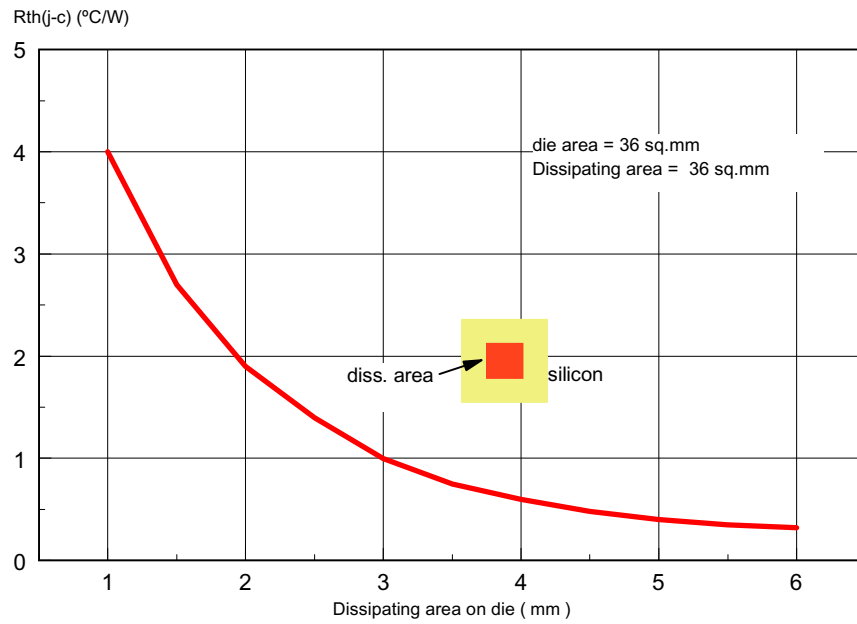
PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.38 mm	3.9 W/cm°C
slug	high thermal conductivity Cu	1.5 mm	3.9 W/cm°C
die attach	soft solder (tin / lead)	15-50 µm	0.5 W/cm°C
molding compound	epoxy resin	5 mm	0.0063W/cm°C

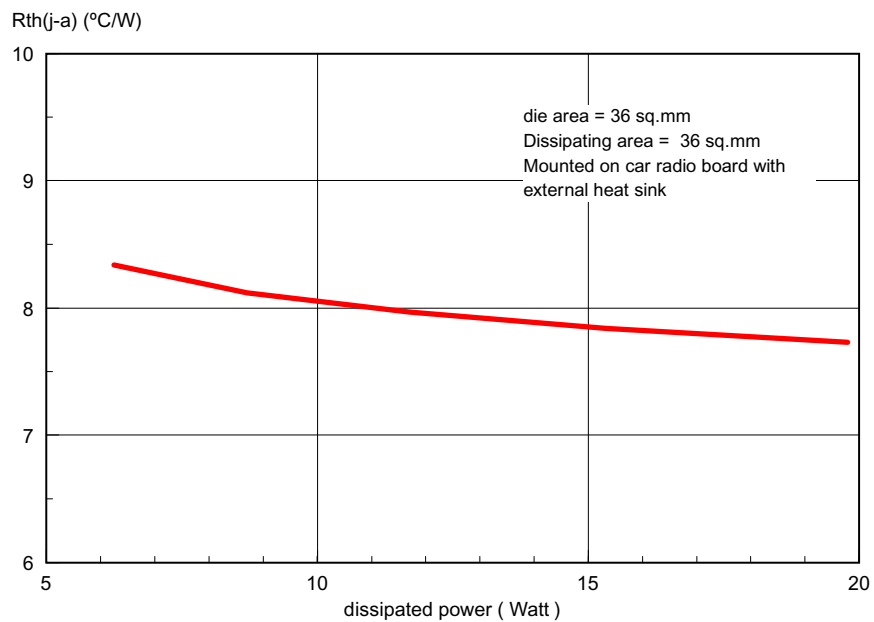
Charts enclosed :

- 1) $R_{th}(j-C)$ vs cold plate
- 1) $R_{th}(j-a)$ vs. on board heat sink area
- 2) $Z_{th}(j-a)$ vs time width

1)



2)



3)

